

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
HEUNG TEAK BAE	03/25/2014
RECEIVING PARTY DATA	
Name:	LG INNOTEK CO., LTD.
Street Address:	SEOUL SQUARE, 541
Internal Address:	NAMDAEMUNNO 5-GA, JUNG-GU
City:	SEOUL
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Postal Code:	100-714
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	14240692
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NAME OF SUBMITTER:	JEFF LLOYD
SIGNATURE:	/JEFF LLOYD/
DATE SIGNED:	05/02/2014
Total Attachments: 2	
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ASSIGNMENT

WHEREAS, I, the undersigned, residing at the indicated addresses given below, respectively, have invented certain new and useful improvements in PROCESS OF SURFACE TREATMENT FOR WAFER, for which an application for United States Letters Patent was filed, as Serial No. 14/240,692, on February 24, 2014.

WHEREAS, **LG INNOTEK CO., LTD.**, a corporation of the country of the Seoul Square, 541, Namdaemunno 5-ga, Jung-gu, Seoul, 100-714, Republic of Korea, is desirous of acquiring the entire right, title, and interest in and to said invention and in and to any Letters Patent which may be granted therefor in the United States and in any and all foreign countries;

NOW, THEREFORE, in view of valuable consideration, receipt of which is hereby acknowledged, I, the undersigned, have sold, assigned, and transferred, and by these presents do sell, as sign, and transfer, unto said **LG INNOTEK CO., LTD.**, its successors and assigns, the full and exclusive right to the said invention in the United States and its territorial possessions and in all foreign countries and the entire right, title, and interest in and to any and all Letters Patent which may be granted therefor in the United States and its territorial possessions and in any and all foreign countries and in and to any and all divisions, reissues, continuations, and extensions thereof.

I hereby authorize and request the Patent Office Officials in the United States and in any and all foreign countries to issue any and all of said Letters Patent, when granted, to **LG INNOTEK CO., LTD.**, as the assignee of the entire right, title, and interest in and to the same, for the sole use and behoof of said **LG INNOTEK CO., LTD.**, its successors and assigns.

FURTHER, I agree that I will communicate to said **LG INNOTEK CO., LTD.**, or its representatives, any facts known to me respecting said invention; testify in any legal proceedings; sign all lawful papers; execute all divisional, continuation, substitution, renewal, and reissue applications; execute all necessary assignment papers to cause any and all of said Letters Patent to be issued to said **LG INNOTEK CO., LTD.**; make all rightful oaths; and generally do everything possible to aid the said **LG INNOTEK CO., LTD.**, its successors and assigns, to obtain and enforce proper protection for said invention in the United States and in any and all foreign countries.

IN TESTIMONY WHEREOF, I have hereunto set my hand this 25 day of
3, 2014.

Signed



BAE, Heung Teak
Seoul Square, 541, Namdaemunno 5-ga,
Jung-gu, Seoul, 100-714,
Republic of Korea

WITNESS

Signature:



Printed Name: KIM, Ji Hye

Date: March 25, 2014